

# DATA SHEET

## **74LVC574**

Octal D-type flip-flop;  
positive edge-trigger (3-State)

Product specification  
Supersedes data of February 1996  
IC24 Data Handbook

1997 Mar 18

# Octal D-type flip-flop; positive edge-trigger (3-State)

74LVC574

## FEATURES

- Wide supply voltage range of 1.2V to 3.6V
- In accordance with JEDEC standard no. 8-1A
- Inputs accept voltages up to 5.5V
- CMOS low power consumption
- Direct interface with TTL levels
- 8-bit positive edge-triggered register
- Independent register and 3-State buffer operation
- Output drive capability 50Ω transmission lines @ 85°C

## DESCRIPTION

The 74LVC574 is a high-performance low-power, low-voltage Si-gate CMOS device and superior to most advanced CMOS compatible TTL families. Inputs can be driven from either 3.3V or 5V devices. This feature allows the use of these devices as translators in a mixed 3.3V/5V environment.

The 74LVC574 is an octal D-type flip-flop featuring separate D-type inputs for each flip-flop and 3-State outputs for bus oriented applications. A clock (CP) and an output enable ( $\overline{OE}$ ) input are common to all flip-flops.

The eight flip-flops will store the state of their individual D-inputs that meet the set-up and hold times requirements on the LOW-to-HIGH CP transition.

When  $\overline{OE}$  is LOW, the contents of the eight flip-flops is available at the outputs. When  $\overline{OE}$  is HIGH, the outputs go to the high impedance OFF-state. Operation of the  $\overline{OE}$  input does not affect the state of the flip-flops. The '574' is functionally identical to the '374' but the '374' has a different pin arrangement.

## QUICK REFERENCE DATA

GND = 0V; T<sub>amb</sub> = 25°C; t<sub>r</sub> = t<sub>f</sub> ≤ 2.5 ns

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t <sub>PHL</sub> /t <sub>PLH</sub>	Propagation delay CP to Q <sub>n</sub>	C <sub>L</sub> = 50pF V <sub>CC</sub> = 3.3V	4.8	ns
f <sub>max</sub>	Maximum clock frequency	C <sub>L</sub> = 50pF V <sub>CC</sub> = 3.3V	150	MHz
C <sub>I</sub>	Input capacitance		5.0	pF
C <sub>PD</sub>	Power dissipation capacitance per flip-flop	Notes 1 and 2	28	pF

### NOTES:

1. C<sub>PD</sub> is used to determine the dynamic power dissipation (P<sub>D</sub> in μW)  
 $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$  where:  
 f<sub>i</sub> = input frequency in MHz; C<sub>L</sub> = output load capacity in pF;  
 f<sub>o</sub> = output frequency in MHz; V<sub>CC</sub> = supply voltage in V;  
 Σ (C<sub>L</sub> × V<sub>CC</sub><sup>2</sup> × f<sub>o</sub>) = sum of the outputs.
2. The condition is V<sub>I</sub> = GND to V<sub>CC</sub>

## ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	PKG. DWG. #
20-Pin Plastic SO	-40°C to +85°C	74LVC574 D	74LVC574 D	SOT163-1
20-Pin Plastic SSOP Type II	-40°C to +85°C	74LVC574 DB	74LVC574 DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to +85°C	74LVC574 PW	74LVC574PW DH	SOT360-1

## PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
1	$\overline{OE}$	Output enabled input (active LOW)
2, 3, 4, 5, 6, 7, 8, 9	D0-D7	Data inputs
19, 18, 17, 16, 15, 14, 13, 12	Q0-Q7	3-State flip-flop outputs
10	GND	Ground (0V)
11	CP	Clock input (LOW-to-HIGH, edge-triggered)
20	VCC	Positive supply voltage

## FUNCTION TABLE

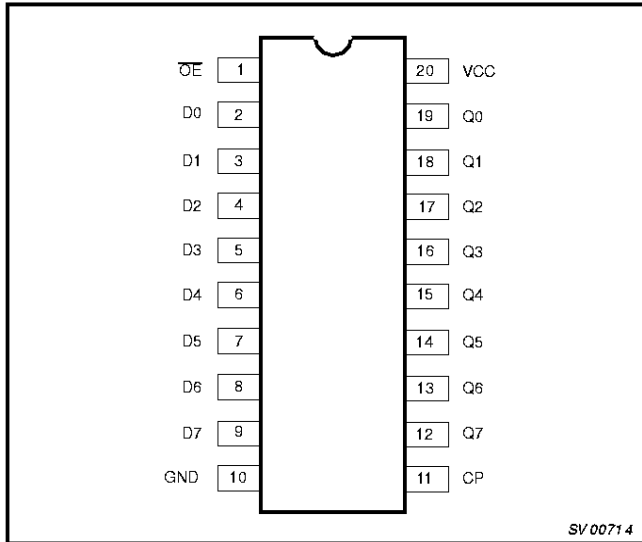
OPERATING MODES	INPUTS			INTERNAL FLIP-FLOPS	OUTPUTS Q0 to Q7
	$\overline{OE}$	CP	D <sub>n</sub>		
Load and read register	L	↑	l	L	L
	L	↑	h	H	H
Load register and disable outputs	H	↑	l	L	Z
	H	↑	h	H	Z

- H = HIGH voltage level
- h = HIGH voltage level one set-up time prior to the LOW-to-HIGH CP transition
- L = LOW voltage level
- l = LOW voltage level one set-up time prior to the LOW-to-HIGH CP transition
- Z = High impedance OFF-state
- ↑ = LOW-to-HIGH clock transition

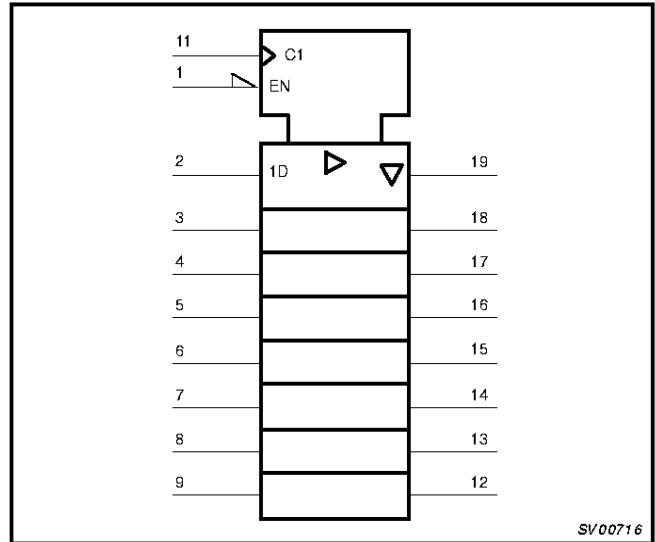
# Octal D-type flip-flop; positive edge-trigger (3-State)

74LVC574

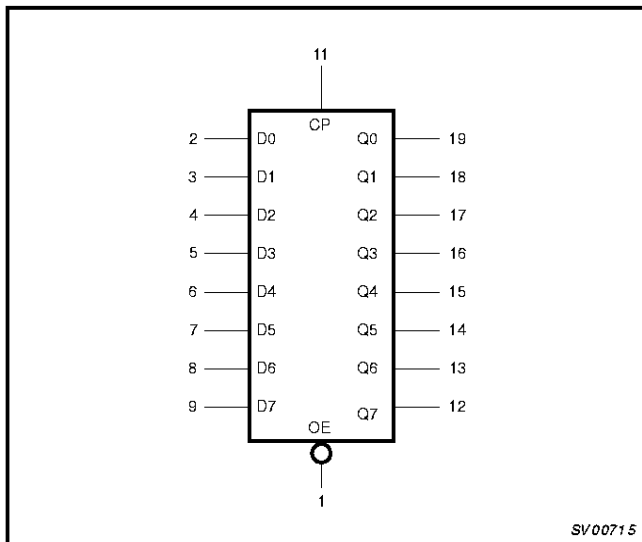
## PIN CONFIGURATION



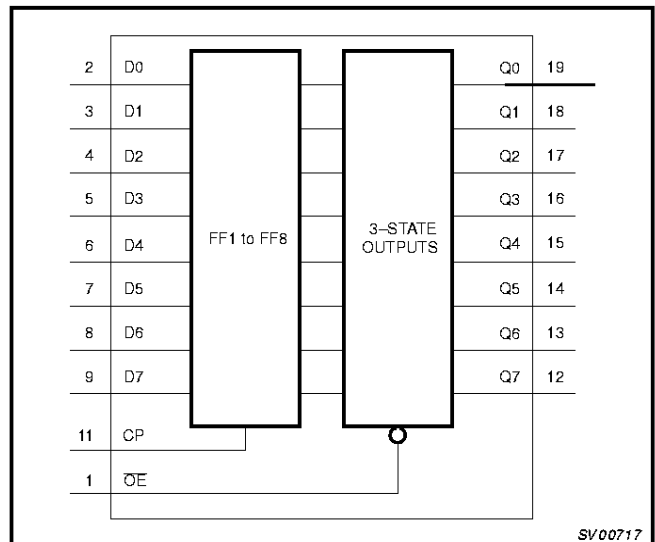
## LOGIC SYMBOL (IEEE/IEC)



## LOGIC SYMBOL



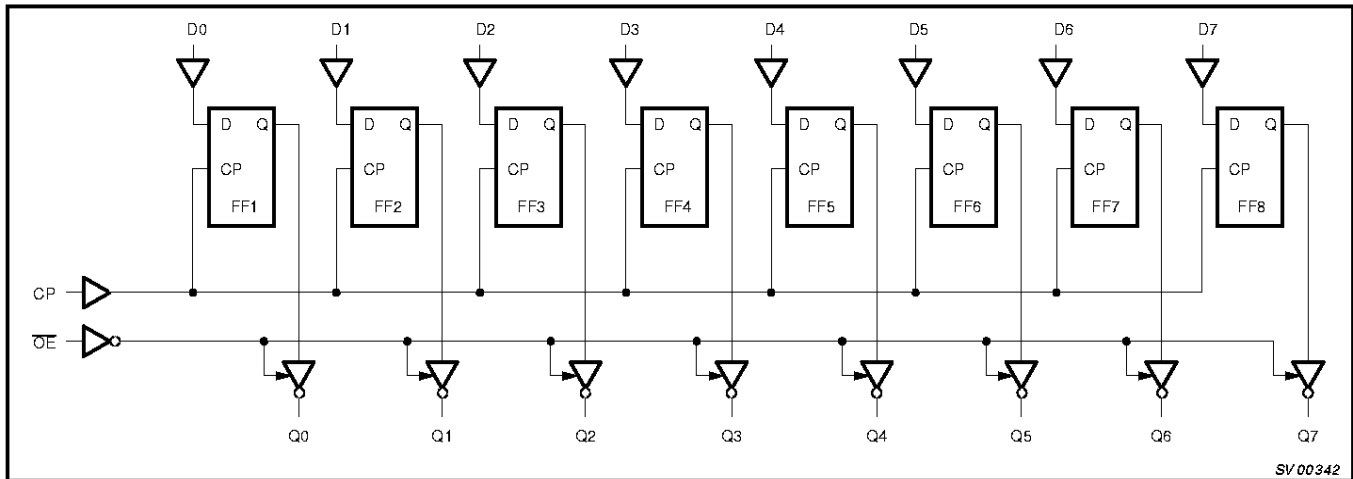
## FUNCTIONAL DIAGRAM



# Octal D-type flip-flop; positive edge-trigger (3-State)

74LVC574

## LOGIC DIAGRAM



## RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	LIMITS		UNIT
			MIN	MAX	
$V_{CC}$	DC supply voltage (for max. speed performance)		2.7	3.6	V
$V_{CC}$	DC supply voltage (for low-voltage applications)		1.2	3.6	V
$V_I$	DC input voltage range		0	5.5	V
$V_{IO}$	DC input voltage range for I/Os		0	$V_{CC}$	V
$V_O$	DC output voltage range		0	$V_{CC}$	V
$T_{amb}$	Operating free-air temperature range		-40	+85	°C
$t_r, t_f$	Input rise and fall times	$V_{CC} = 1.2$ to $2.7V$ $V_{CC} = 2.7$ to $3.6V$	0	20 10	ns/V

## ABSOLUTE MAXIMUM RATINGS<sup>1</sup>

In accordance with the Absolute Maximum Rating System (IEC 134).  
 Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
$V_{CC}$	DC supply voltage		-0.5 to +6.5	V
$I_{IK}$	DC input diode current	$V_I < 0$	-50	mA
$V_I$	DC input voltage	Note 2	-0.5 to +5.5	V
$V_{IO}$	DC input voltage range for I/Os		-0.5 to $V_{CC} + 0.5$	V
$I_{OK}$	DC output diode current	$V_O > V_{CC}$ or $V_O < 0$	$\pm 50$	mA
$V_{OUT}$	DC output voltage	Note 2	-0.5 to $V_{CC} + 0.5$	V
$I_{OUT}$	DC output source or sink current	$V_O = 0$ to $V_{CC}$	$\pm 50$	mA
$I_{GND}, I_{CC}$	DC $V_{CC}$ or GND current		$\pm 100$	mA
$T_{stg}$	Storage temperature range		-60 to +150	°C
$P_{TOT}$	Power dissipation per package - plastic mini-pack (SO) - plastic shrink mini-pack (SSOP and TSSOP)	above +70°C derate linearly with 8 mW/K above +60°C derate linearly with 5.5 mW/K	500 500	mW

### NOTES:

- Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

## Octal D-type flip-flop; positive edge-trigger (3-State)

74LVC574

**DC ELECTRICAL CHARACTERISTICS**

Over recommended operating conditions. Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			Temp = -40°C to +85°C			
			MIN	TYP <sup>1</sup>	MAX	
V <sub>IH</sub>	HIGH level Input voltage	V <sub>CC</sub> = 1.2V	V <sub>CC</sub>			V
		V <sub>CC</sub> = 2.7 to 3.6V	2.0			
V <sub>IL</sub>	LOW level Input voltage	V <sub>CC</sub> = 1.2V			GND	V
		V <sub>CC</sub> = 2.7 to 3.6V			0.8	
V <sub>OH</sub>	HIGH level output voltage	V <sub>CC</sub> = 2.7V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = -12mA	V <sub>CC</sub> - 0.5			V
		V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = -100µA	V <sub>CC</sub> - 0.2	V <sub>CC</sub>		
		V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = -12mA	V <sub>CC</sub> - 0.6			
		V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = -24mA	V <sub>CC</sub> - 1.0			
V <sub>OL</sub>	LOW level output voltage	V <sub>CC</sub> = 2.7V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = 12mA			0.40	V
		V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = 100µA		0	0.20	
		V <sub>CC</sub> = 3.0V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; I <sub>O</sub> = 24mA			0.55	
I <sub>I</sub>	Input leakage current	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = 5.5V or GND   Not for I/O pins		±0.1	±5	µA
I <sub>IHZ</sub> /I <sub>ILZ</sub>	Input current for common I/O pins	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = V <sub>CC</sub> or GND		±0.1	±15	µA
I <sub>OZ</sub>	3-State output OFF-state current	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub> ; V <sub>O</sub> = V <sub>CC</sub> or GND		0.1	±10	µA
I <sub>CC</sub>	Quiescent supply current	V <sub>CC</sub> = 3.6V; V <sub>I</sub> = V <sub>CC</sub> or GND; I <sub>O</sub> = 0		0.1	20	µA
ΔI <sub>CC</sub>	Additional quiescent supply current per input pin	V <sub>CC</sub> = 2.7V to 3.6V; V <sub>I</sub> = V <sub>CC</sub> - 0.6V; I <sub>O</sub> = 0		5	500	µA

**NOTE:**1. All typical values are at V<sub>CC</sub> = 3.3V and T<sub>amb</sub> = 25°C.**AC CHARACTERISTICS**GND = 0 V; t<sub>r</sub> = t<sub>f</sub> ≤ 2.5 ns; C<sub>L</sub> = 50 pF

SYMBOL	PARAMETER	WAVEFORM	LIMITS						UNIT
			V <sub>CC</sub> = 3.3V ±0.3V			V <sub>CC</sub> = 2.7V		V <sub>CC</sub> = 1.2V	
			MIN	TYP <sup>1</sup>	MAX	MIN	MAX	TYP	
t <sub>PHL</sub> /t <sub>PLH</sub>	Propagation delay CP to Qn	Figures 1, 4	1.5	4.8	8.5	1.5	9.5	21	ns
t <sub>PZH</sub> /t <sub>PZL</sub>	3-State output enable time OE to Qn	Figures 2, 4	1.5	4.0	7.5	1.5	8.0	17	ns
t <sub>PHZ</sub> /t <sub>PLZ</sub>	3-State output disable time OE to Qn	Figures 2, 4	1.5	3.5	6.0	1.5	6.5	8.0	ns
t <sub>w</sub>	Clock pulse width HIGH or LOW	Figure 1	–	3.0	–	–	–	–	ns
t <sub>su</sub>	Set-up time Dn to CP	Figure 3	1.0	0.3	–	1.0	–	–	ns
t <sub>h</sub>	Hold time Dn to CP	Figure 3	1.0	-0.2	–	1.0	–	–	ns
f <sub>max</sub>	Maximum clock pulse frequency	Figure 1	75	150	–	–	–	–	MHz

**NOTE:**1. These typical values are at V<sub>CC</sub> = 3.3V and T<sub>amb</sub> = 25°C.

# Octal D-type flip-flop; positive edge-trigger (3-State)

74LVC574

### AC WAVEFORMS

$V_M = 1.5V$  at  $V_{CC} \geq 2.7V$

$V_M = 0.5V \cdot V_{CC}$  at  $V_{CC} < 2.7V$

$V_{OL}$  and  $V_{OH}$  are the typical output voltage drop that occur with the output load.

$V_X = V_{OL} + 0.3V$  at  $V_{CC} \geq 2.7V$ ;  $V_X = V_{OL} + 0.1V_{CC}$  at  $V_{CC} < 2.7V$

$V_Y = V_{OH} - 0.3V$  at  $V_{CC} \geq 2.7V$ ;  $V_Y = V_{OH} - 0.1V_{CC}$  at  $V_{CC} < 2.7V$

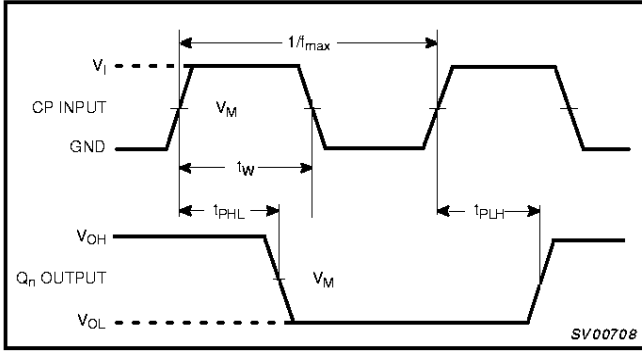


Figure 1. Clock (CP) to output (Qn) propagation delays, the clock pulse (CP), and the maximum clock pulse frequency

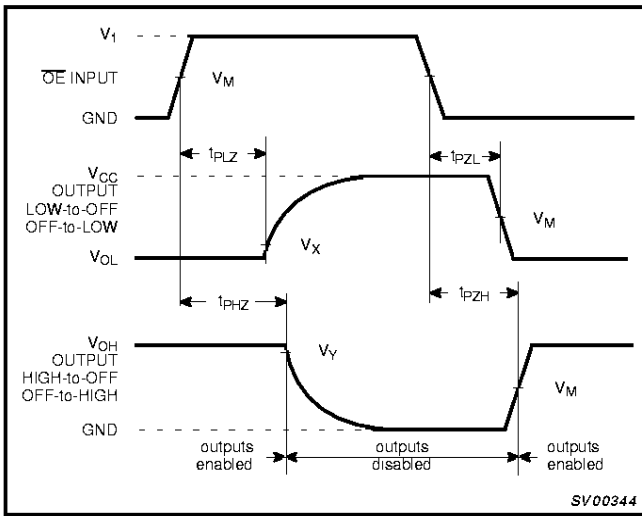


Figure 2. 3-State enable and disable times

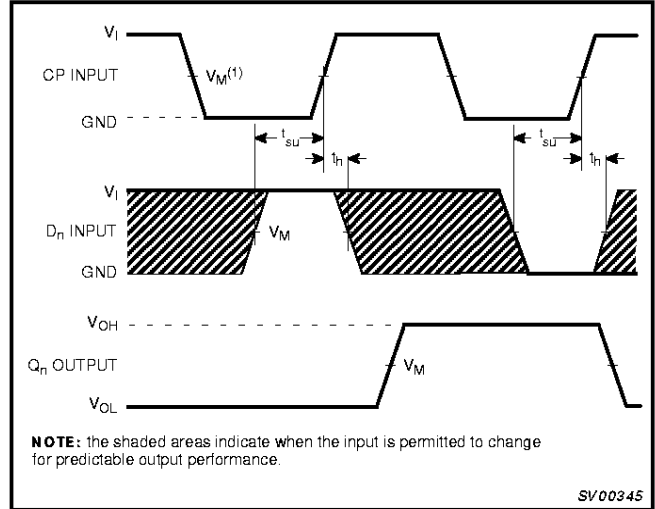


Figure 3. Data set-up and hold times for the Dn input to the CP input

### TEST CIRCUIT

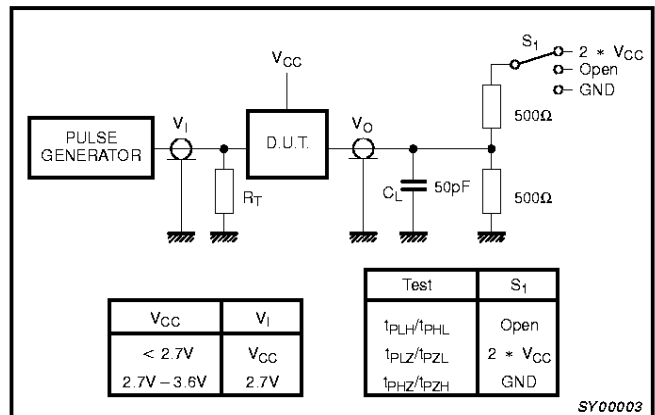


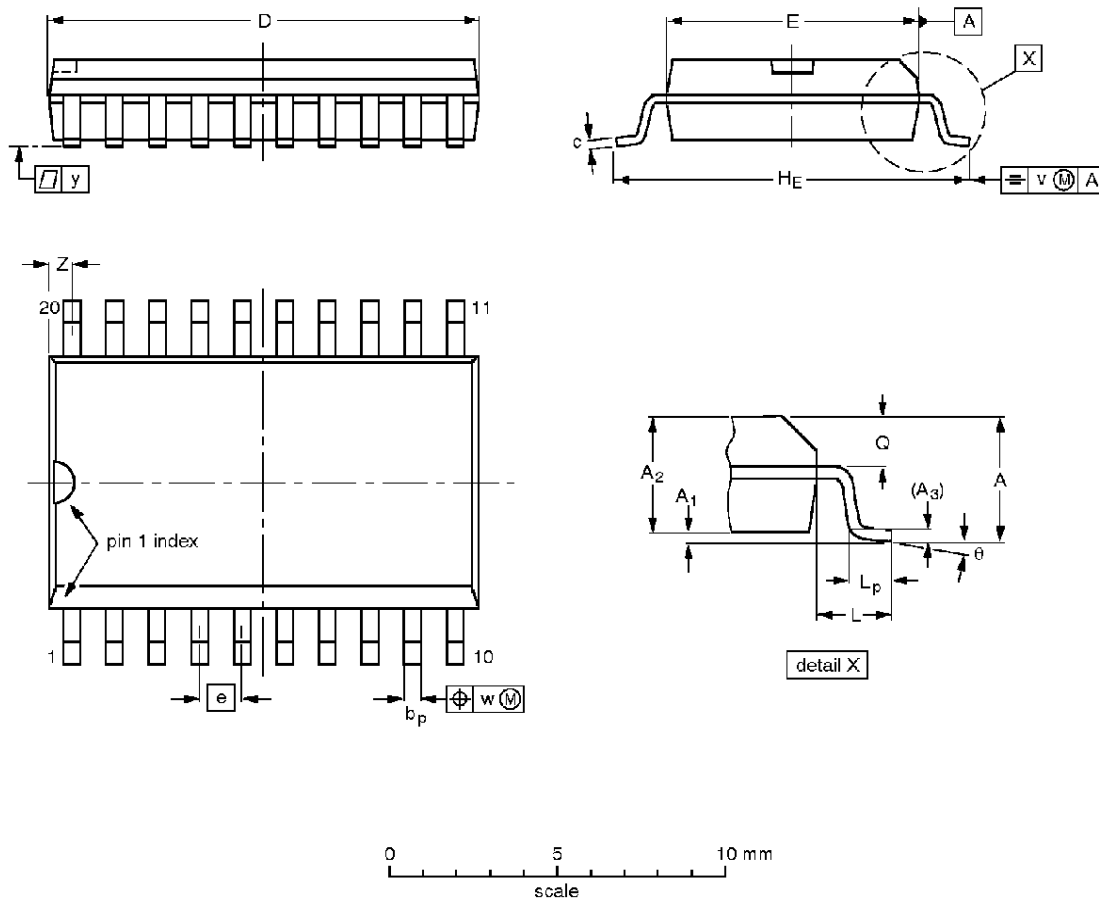
Figure 4. Load circuitry for switching times

# Octal D-type flip-flop; positive edge-trigger (3-State)

74LVC574

**SO20:** plastic small outline package; 20 leads; body width 7.5 mm

**SOT163-1**



**DIMENSIONS (inch dimensions are derived from the original mm dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.85 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

**Note**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

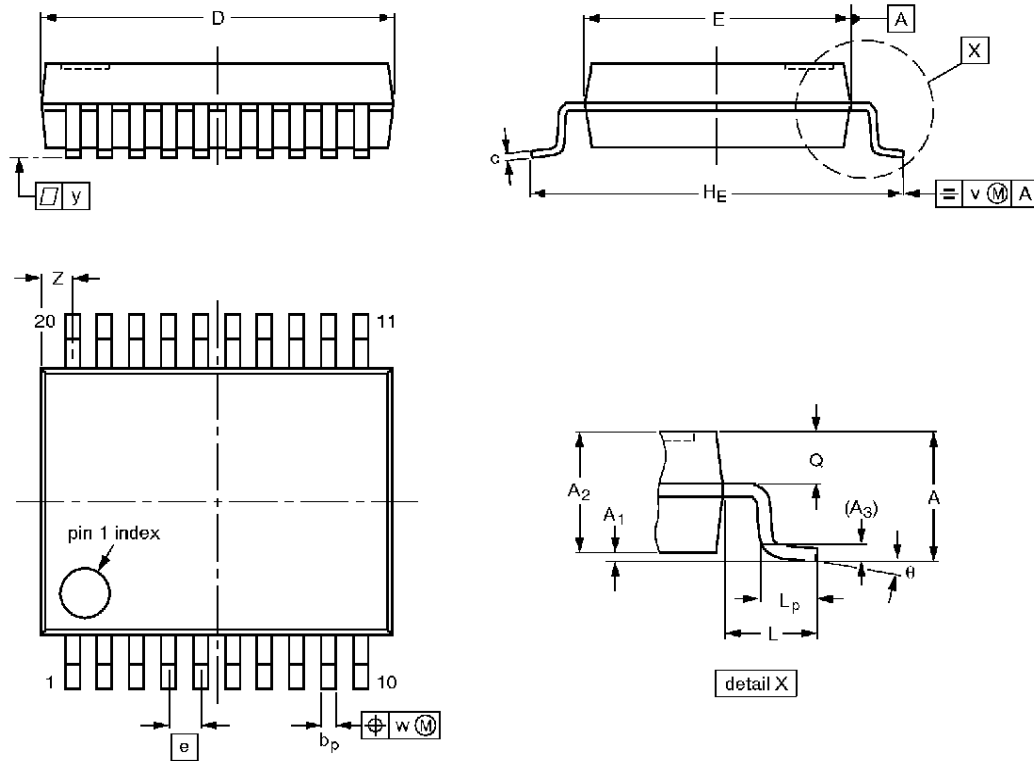
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT163-1	075E04	MS-013AC				92-11-17 95-01-24

Octal D-type flip-flop; positive edge-trigger (3-State)

74LVC574

SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

**Note**

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT339-1		MO-150AE				93-09-08 95-02-04

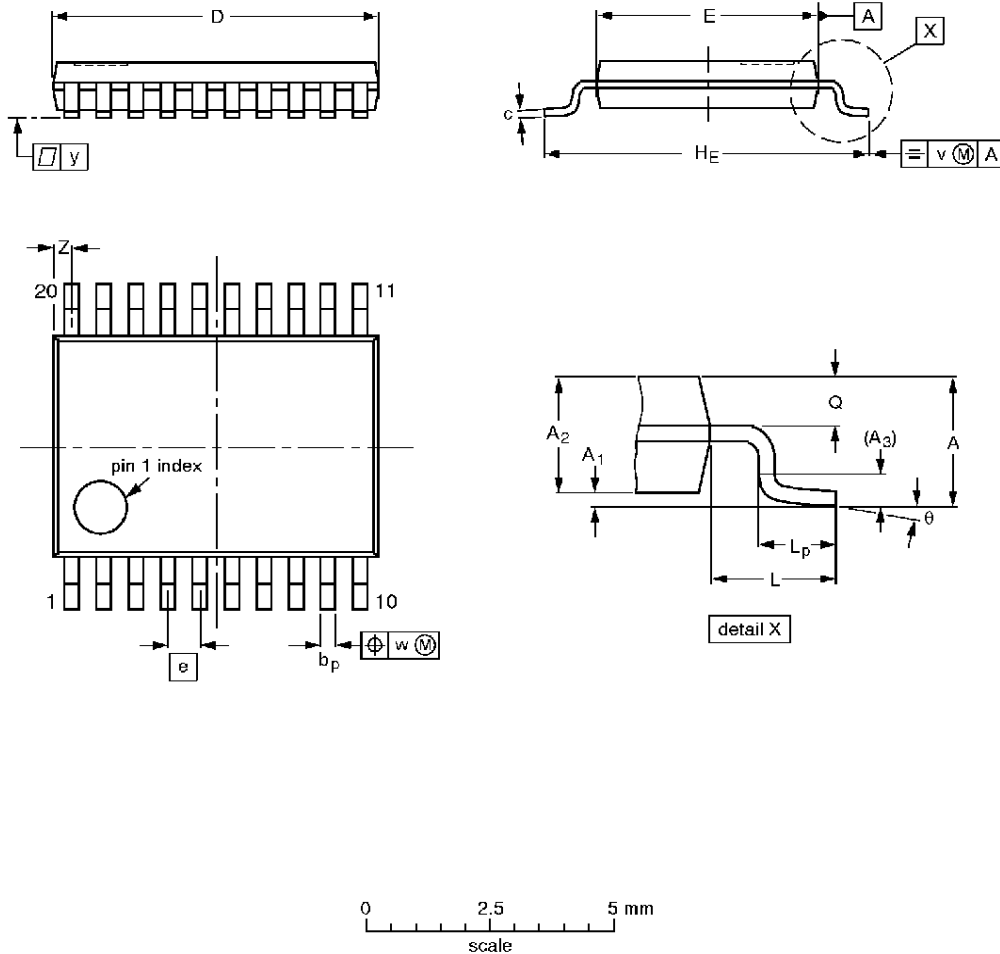


Octal D-type flip-flop; positive edge-trigger (3-State)

74LVC574

TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



**DIMENSIONS (mm are the original dimensions)**

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	A <sub>3</sub>	b <sub>p</sub>	c	D <sup>(1)</sup>	E <sup>(2)</sup>	e	H <sub>E</sub>	L	L <sub>p</sub>	Q	v	w	y	Z <sup>(1)</sup>	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

**Notes**

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT360-1		MO-153AC				-93-06-16 95-02-04

Octal D-type flip-flop; positive edge-trigger (3-State)

74LVC574

**DEFINITIONS**

Data Sheet Identification	Product Status	Definition
<i>Objective Specification</i>	<b>Formative or In Design</b>	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
<i>Preliminary Specification</i>	<b>Preproduction Product</b>	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
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